# CY7C187



# 64K x 1 Static RAM

### Features

- High speed
  - 15 ns
- CMOS for optimum speed/power
- Low active power
  - 495 mW
- · Low standby power
  - 110 mW
- TTL compatible inputs and outputs

Logic Block Diagram

- · Automatic power-down when deselected
- Available in Pb-free and non Pb-free 22-pin (300-Mil) Molded DIP and 24-pin (300-Mil) Molded SOJ

# **Functional Description**

The CY7C187 is a high-performance CMOS static RAM organized as 65,536 words x 1 bit. Easy memory expansion is provided by an active LOW Chip Enable (CE) and tri-state drivers. The CY7C187 has an automatic power-down feature, reducing the power consumption by 56% when deselected.

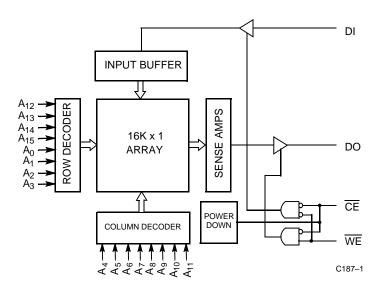
<u>Writing</u> to the device is <u>accomplished</u> when the Chip Enable  $\overline{(CE)}$  and Write Enable  $\overline{(WE)}$  inputs are both LOW. Data on the input pin  $(D_{IN})$  is written into the memory location specified on the address pins  $(A_0 \text{ through } A_{15})$ .

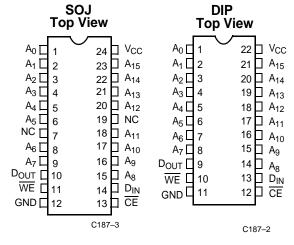
<u>Rea</u>ding the device is accomplished by taking the Chip Enable  $(\overline{CE})$  LOW, while Write Enable (WE) remains HIGH. Under these conditions, the contents of the memory location specified on the address pin will appear on the data output  $(D_{OUT})$  pin.

The out<u>put</u> pin stays in high-impedance state when Chip Enable (CE) is HIGH or Write Enable (WE) is LOW.

The CY7C187 utilizes a die coat to insure alpha immunity.

# **Pin Configurations**





### Selection Guide

	-15	-25	-35
Maximum Access Time (ns)	15	25	35
Maximum Operating Current (mA)	90	70	70
Maximum CMOS Standby Current (mA)	20	20	20

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# CY7C187

# **Maximum Ratings**

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature	–65°C to +150°C
Ambient Temperature with Power Applied	–55°C to +125°C
Supply Voltage to Ground Potential (Pin 22 to Pin 11)	0.5V to +7.0V
DC Voltage Applied to Outputs in High Z State <sup>[1]</sup>	–0.5V to +7.0V

# DC Input Voltage<sup>[1]</sup>....-0.5V to +7.0V Output Current into Outputs (LOW)......20 mA Static Discharge Voltage.....>2001V (per MIL–STD–883, Method 3015) Latch-Up Current.....>200 mA

## **Operating Range**

Range	Ambient Temperature	v <sub>cc</sub>
Commercial	0°C to +70°C	$5V \pm 10\%$

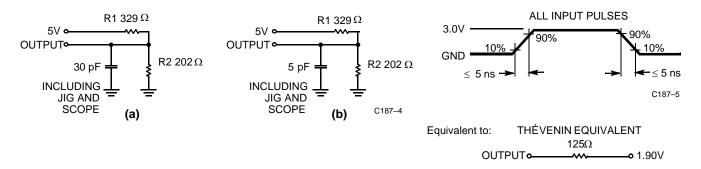
**Electrical Characteristics** Over the Operating Range

			-	15	-25 a	nd -35	
Parameter	Description	Test Conditions	Min.	Max.	Min. Max.		Unit
V <sub>OH</sub>	Output HIGH Voltage	$V_{CC}$ = Min., $I_{OH}$ = -4.0mA	2.4		2.4		V
V <sub>OL</sub>	Output LOW Voltage	$V_{CC} = Min., I_{OL} = 12.0 \text{ mA}$		0.4		0.4	V
V <sub>IH</sub>	Input HIGH Voltage		2.2	V <sub>CC</sub>	2.2	V <sub>CC</sub>	V
V <sub>IL</sub>	Input LOW Voltage <sup>[1]</sup>		-0.5	0.8	-0.5	0.8	V
I <sub>IX</sub>	Input Leakage Current	$GND \le V_I \le V_{CC}$	-5	+5	-5	+5	μΑ
I <sub>OZ</sub>	Output Leakage Current	$\begin{array}{l} \text{GND} \leq \text{V}_{O} \leq \text{V}_{CC}, \\ \text{Output Disabled} \end{array}$	-5	+5	-5	+5	μΑ
I <sub>CC</sub>	V <sub>CC</sub> Operating Supply Current	V <sub>CC</sub> = Max., I <sub>OUT</sub> = 0 mA		90		70	mA
I <sub>SB1</sub>	Automatic CE Power- Down Current <sup>[3]</sup>	Max. $V_{CC}$ , $\overline{CE} \ge V_{IH}$		40		20	mA
I <sub>SB2</sub>	Automatic CE Power-Down Current	$\begin{array}{l} \mbox{Max. V}_{CC}, \ensuremath{\overline{CE}} \geq V_{CC} - 0.3 \ensuremath{V_{IN}} \geq V_{CC} - 0.3 \ensuremath{V_{OC}} \\ \ensuremath{v_{IN}} \leq 0.3 \ensuremath{V} \end{array}$		20		20	mA

### Capacitance<sup>[4]</sup>

Parameter	Description	Test Conditions	Max.	Unit
C <sub>IN</sub>	Input Capacitance	$T_{A} = 25^{\circ}C, f = 1 \text{ MHz},$	10	pF
C <sub>OUT</sub>	Output Capacitance	$V_{CC} = 5.0V$	10	pF

### **AC Test Loads and Waveforms**



#### Notes:

- 1.  $V_{IL}$  (min.) = -3.0V for pulse durations less than 30 ns.
- 2. Not more than 1 output should be shorted at one time. Duration of the short circuit should not exceed 30 seconds.
- 3. A pull-up resistor to  $V_{CC}$  on the  $\overline{CE}$  input is required to keep the device deselected during  $V_{CC}$  power-up, otherwise I<sub>SB</sub> will exceed values given.
- 4. Tested initially and after any design or process changes that may affect these parameters.

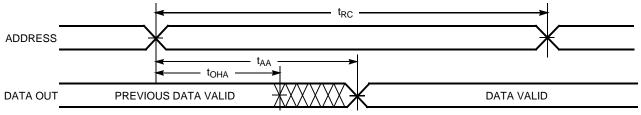


		-	15	-:	25	-:	35	
Parameter Description		Min.	Max.	Min.	Max.	Min.	Max.	Unit
READ CYCLI	E			•	•	•	•	
t <sub>RC</sub>	Read Cycle Time	15		25		35		ns
t <sub>AA</sub>	Address to Data Valid		15		25		35	ns
t <sub>OHA</sub>	Output Hold from Address Change	3		5		5		ns
t <sub>ACE</sub>	CE LOW to Data Valid		15		25		35	ns
t <sub>LZCE</sub>	CE LOW to Low Z <sup>[6]</sup>	3		5		5		ns
t <sub>HZCE</sub>	CE HIGH to High Z <sup>[6, 7]</sup>		8		10		15	ns
t <sub>PU</sub>	CE LOW to Power Up	0		0		0		ns
t <sub>PD</sub>	CE HIGH to Power Down		15		20		20	ns
WRITE CYCL	<b>E</b> <sup>[8]</sup>							
t <sub>WC</sub>	Write Cycle Time	15		20		25		ns
t <sub>SCE</sub>	CE LOW to Write End	12		20		25		ns
t <sub>AW</sub>	Address Set-Up to Write End	12		20		25		ns
t <sub>HA</sub>	Address Hold from Write End	0		0		0		ns
t <sub>SA</sub>	Address Set-Up to Write Start	0		0		0		ns
t <sub>PWE</sub>	WE Pulse Width	12		15		20		ns
t <sub>SD</sub>	Data Set-Up to Write End	10		10		15		ns
t <sub>HD</sub>	Data Hold from Write End	0		0		0		ns
t <sub>LZWE</sub>	WE HIGH to Low Z	5		5		5		ns
t <sub>HZWE</sub>	WE LOW to High Z <sup>[7]</sup>		7		7		10	ns

### Switching Characteristics Over the Operating Range<sup>[5]</sup>

## **Switching Waveforms**

Read Cycle No. 1<sup>[9, 10]</sup>



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#### Notes:

- 5. Test conditions assume signal transition time of 5 ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V, and output loading of the specified I<sub>OL</sub>/I<sub>OH</sub> and 30-pF load capacitance.

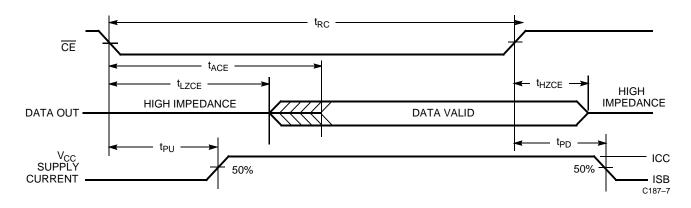
6. At any given temperature and voltage condition, t<sub>HZCE</sub> is less than t<sub>LZCE</sub> for any given device.
7. t<sub>HZCE</sub> and t<sub>HZWE</sub> are specified with C<sub>L</sub> = 5 pF as in part (b) of AC Test Loads. Transition is measured ±500 mV from steady-state voltage.
8. The internal write time of the memory is defined by the overlap of CE LOW and WE LOW. Both signals must be LOW to initiate a write and either signal can terminate a write by going HIGH. The data input set-up and hold timing should be referenced to the rising edge of the signal that terminates the write.
9. WE is HIGH for read cycle.

10. Device is continuously selected,  $\overline{CE} = V_{IL}$ .

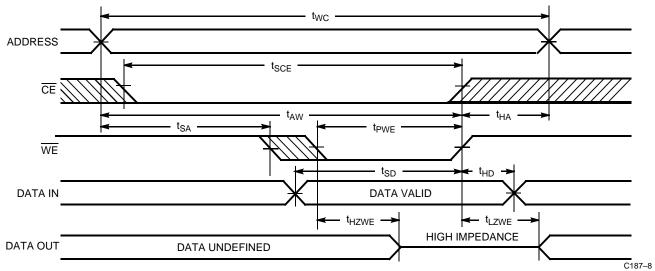


# **Switching Waveforms**

Read Cycle No. 2<sup>[9, 11]</sup>



# Write Cycle No. 1(WE Controlled)<sup>[11]</sup>



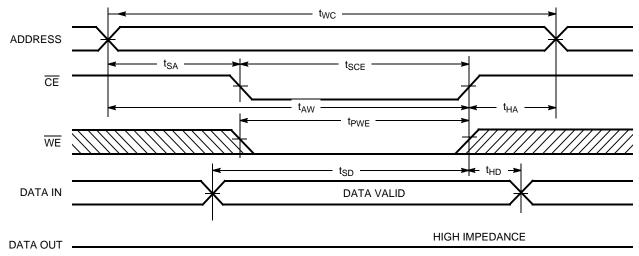
#### Note:

11. Address valid prior to or coincident with  $\overline{CE}$  transition LOW.



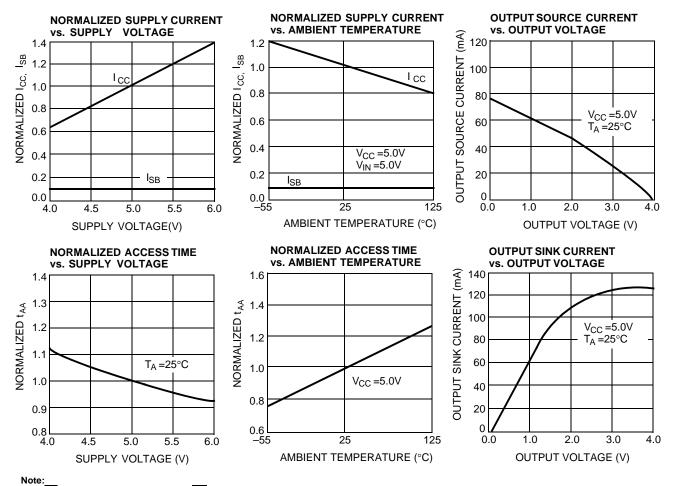
# **Switching Waveforms**

Write Cycle No. 2(CE Controlled)<sup>[11,13]</sup>



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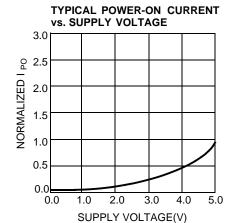
# **Typical DC and AC Characteristics**

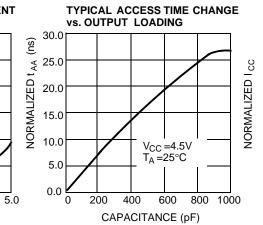


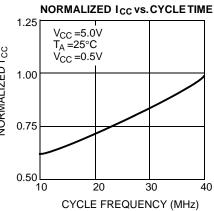
12. If CE goes HIGH simultaneously with WE HIGH, the output remains in a high-impedance state.



## Typical DC and AC Characteristics (Continued)







### **Address Designators**

Address Name	Address Function	Pin Number
A0	X3	1
A1	X4	2
A2	X5	3
A3	X6	4
A4	X7	5
A5	Y7	6
A6	Y6	7
A7	Y2	8
A8	Y3	14
A9	Y1	15
A10	Y0	16
A11	Y4	17
A12	Y5	18
A13	X0	19
A14	X1	20
A15	X2	21

### **Truth Table**

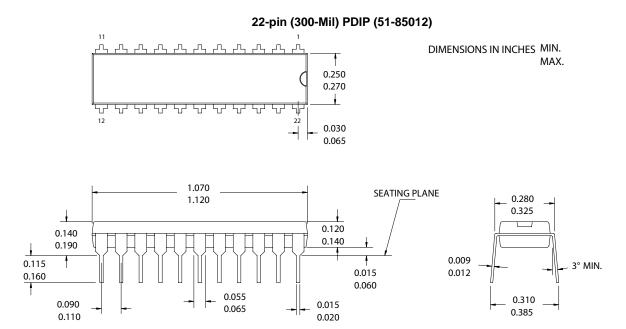
CE	WE	Input/Output	Mode
Н	Х	High Z	Deselect/Power-Down
L	Н	Data Out	Read
L	L	Data In	Write



### **Ordering Information**

Speed (ns)	Ordering Code	Package Diagram	Package Type	Operating Range
15	CY7C187-15PXC	51-85012	22-pin (300-Mil) Molded DIP (Pb-free)	Commercial
25	CY7C187-25PC	51-85012	22-pin (300-Mil) Molded DIP	Commercial
	CY7C187-25VC	51-85030	24-pin (300-Mil) Molded SOJ	
	CY7C187-25VXC		24-pin (300-Mil) Molded SOJ (Pb-free)	
35	CY7C187-35VXC	51-85030	24-pin (300-Mil) Molded SOJ (Pb-free)	Commercial

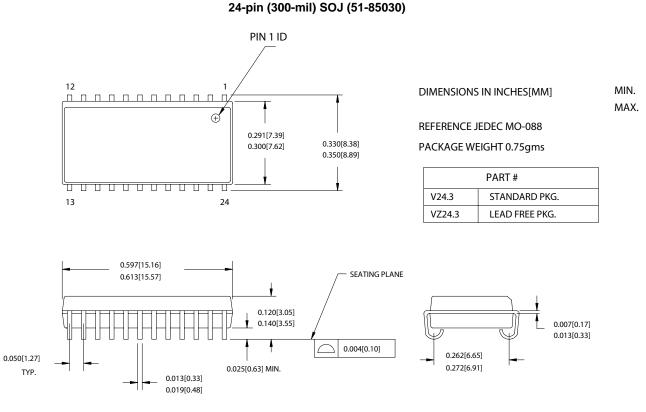
# Package Diagrams



51-85012-\*A



# Package Diagrams (Continued)



51-85030-\*B

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# **Document History Page**

Document Title: CY7C187 64K x 1 Static RAM Document Number: 38-05044						
REV.	ECN NO.	Issue Date	Orig. of Change	Description of Change		
**	107146	09/10/01	SZV	Change from Spec number: 38-00038 to 38-05044		
*A	486744	See ECN	NXR	Removed 20 ns speed bin Changed Low standby power from 220mW to 110mW Changed the description of $I_{IX}$ from Input Load Current to Input Leakage Current in DC Electrical Characteristics table Updated the Ordering Information Table		